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(54) **SEMICONDUCTOR PACKAGE**

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(57) **ABSTRACT**

A semiconductor package may include a substrate; at least one controller chip on the substrate; at least one chip structure on the substrate, the at least one chip structure including a buffer chip, an upper chip stack on the buffer chip, and a lower chip stack below the buffer chip; an upper wire electrically connecting the upper chip stack, the buffer chip, and the at least one controller chip; a lower wire electrically connecting the lower chip stack and the at least one controller chip; a connection wire electrically connecting the at least one controller chip to the substrate; and connection bumps below the substrate, the connection bumps being electrically connected to the at least one controller chip and the at least one chip structure.